

SIR680DP-T1-RE3-VB Datasheet N-Channel 85V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V) R _{DS(on)} (Ω) I _D				
95	0.003at V _{GS} = 10 V	140		
85	0.004at V _{GS} = 4.5 V	130		

FEATURES

- 175 °C Junction Temperature
- SGT technology Power MOSFET

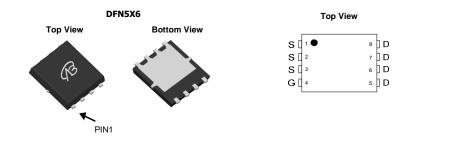
G C

D

N-Channel MOSFET

Material categorization:





ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Gate-Source Voltage	V _{GS}	±20	V		
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C		140	-	
	T _C = 100 °C	^I D	85 ^a		
Pulsed Drain Current	I _{DM}	420	А		
Continuous Source Current (Diode Conduction)	۱ _S	80 ^a			
Avalanche Current	I _{AS}	70	1		
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	133	mJ	
Maximum Dawar Dissinction	T _C = 25 °C	Р	136	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	3 ^b , 8.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \le 10 \text{ sec}$	R _{thJA}	15	18	°C/W
Maximum Junction-to-Ambient*	Steady State		40	50	
Maximum Junction-to-Case		R _{thJC}	0.85	1.1	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t \leq 10 s.

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Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static				.,,,,,			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 µA	85				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V _{DS} = 30V, V _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0 V, T _J = 125 °C			50		
		V _{DS} = 30V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			А	
		V _{GS} = 10 V, I _D = 20 A		0.003			
	P	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		0	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		Ω	
		V _{GS} = 4.5 V, I _D = 46 A		0.004		1	
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic							
Input Capacitance	C _{iss}			8600			
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 85 V, f = 1 MHz		470		pF	
Reverse Transfer Capacitance	C _{rss}			225			
Total Gate Charge ^c	Qg			92	70		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 85 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		16		nC	
Gate-Drain Charge ^c	Q _{gd}			19			
Turn-On Delay Time ^c	t _{d(on)}			20	21		
Rise Time ^c	t _r	V_{DD} = 85 V, R_L = 0.6 Ω		15	25	20	
Turn-Off Delay Time ^c	t _{d(off)}	$\text{I}_\text{D} \cong$ 50 A, V_GEN = 10 V, R_g = 2.5 Ω		35	50	ns	
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics ($T_{\rm C} = 25 \ ^{\circ}{\rm C}$)					
Pulsed Current	I _{SM}				420	А	
Diode Forward Voltage	V _{SD}	$I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

Notes:

a. For design aid only; not subject to production testing.

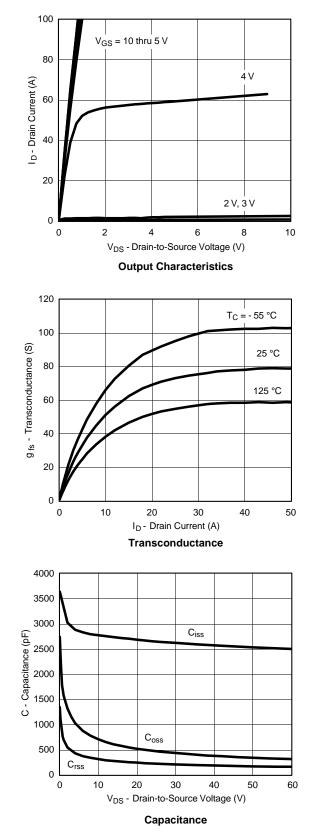
b. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

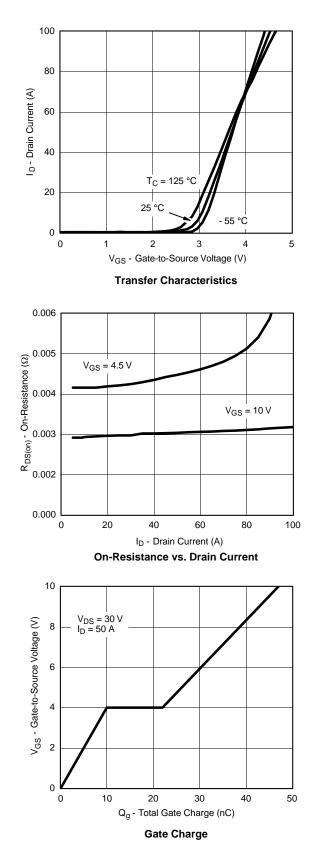
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



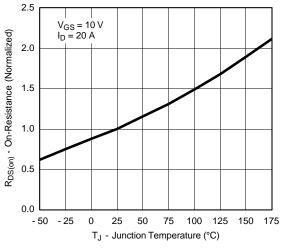
TYPICAL CHARACTERISTICS (25 °C unless noted)



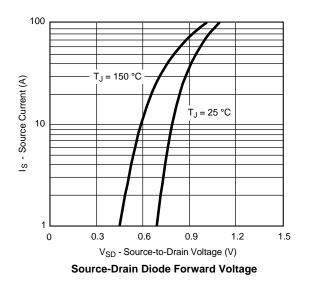




TYPICAL CHARACTERISTICS (25 °C unless noted)



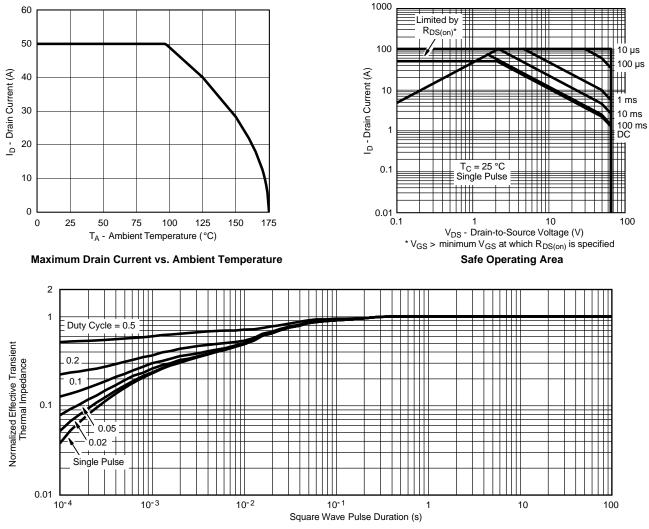
On-Resistance vs. Junction Temperature



SIR680DP-T1-RE3-VB

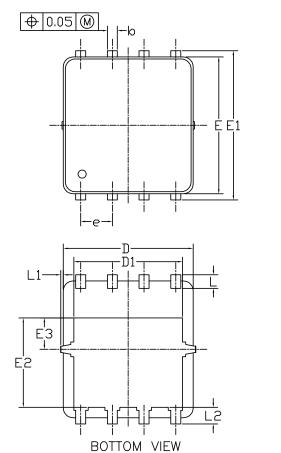


THERMAL RATINGS

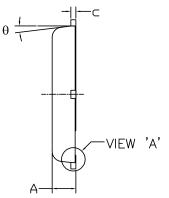


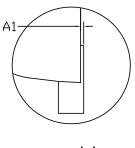
Normalized Thermal Transient Impedance, Junction-to-Case





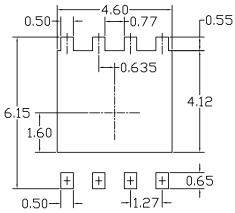
DFN5x6_8L_EP1_P PACKAGE OUTLIN





<u>VIEW 'A'</u> (SCALE 5:1)

RECOMMENDED LAND PATTERN



STA DOL S	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.85	0.95	1.00	0.033	0.037	0.039
Al	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
с	0.15	0.20	0.25	0.006	0.008	0.010
D	5.10	5.20	5.30	0.201	0.205	0.209
D1	4.25	4.35	4.45	0.167	0.171	0.175
Е	5.45	5.55	5.65	0.215	0.219	0.222
E1	5.95	6.05	6.15	0.234	0.238	0.242
E2	3.525	3.625	3.725	0.139	0.143	0.147
E3	1.175	1.275	1.375	0.046	0.050	0.054
e	1.27 BSC			0.050 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0		0.15	0		0.006
L2	0.68 REF			0.027 REF		
θ	0°		10°	0°		10°

UNIT: mm

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.

MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH. 2. CONTROLLING DIMENSION IS MILLIMETER.

CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

NOTE



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